

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	367	(361/718).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:07
L5	1189	(361/706-708).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:25
L6	231	(361/708).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:22
L8	123	5 and ((heat adj spreader) sinkheat-spreaders)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:28
L9	1905	(257/707,717).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:28
L10	251	9 and ((heat adj spreader) sinkheat-spreaders)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:29
L11	224	10 not 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/01 16:29
S3	1016	heat adj spreader and chip\$1 and cooling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/29 18:32

S4	364	S3 and gap\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/29 18:32
S5	162	S4 and (filler (thermally adj conductive adj material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/29 18:55
S6	471	gap and (multichip multi-chip) and (filler (thermally adj conductive adj material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/29 18:57
S7	568	gap\$1 and (multichip multi-chip) and (filler (thermally adj conductive adj material))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/29 18:58
S8	298	S7 and cooling	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/29 18:59